

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/716191	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/12 17:42
S3	3687	S2 and ("204" "205").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/12 17:43
S4	1488	S3 and (semiconductor microelectronics wafer substrate) same copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/12 17:44
S6	32	("3267010" "3328273" "3770598" "3948502" "4085016" "4165252" "4166536" "4192729" "4651440" "4734179" "5013015" "5024746" "5078852" "5167792" "5168886" "5168887" "5228967" "5232511" "5235995" "5238500" "5312532" "5332445" "5342495" "5405518" "5431421" "5445172" "5447615" "5500081" "5503730" "5522975" "5980706" "5985126").PN.	US-PGPUB; USPAT	OR	ON	2006/08/12 18:03
S7	1169	bacon.in.	US-PGPUB; USPAT	OR	ON	2006/08/12 18:04
S8	19	bacon.in. and wafer	US-PGPUB; USPAT	OR	ON	2006/08/12 18:04
S5	203	S4 and weir	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:32
S10	3687	S9 and ("204" "205").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:32

## EAST Search History

S12	203	S11 and weir	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:32
S9	32284	(electroplating plating) and (diffuser diffusion)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:37
S11	1488	S10 and (semiconductor microelectronics wafer substrate) same copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:50
S14	76	(electroplating plating) and flow adj distributor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:50
S15	2700	(electroplating plating) and (fluid solution electrolyte) near3 distribut\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:50
S13	125	S12 not semitool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:51
S16	727	S15 and (semiconductor microelectronics wafer substrate) same copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:51
S17	637	S16 not semitool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:52

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S18	332	S17 and (diffus\$3 distributor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 12:52
L8	2	"4304641".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 14:46
L13	17	("4391694").URPN.	USPAT	OR	ON	2006/08/14 15:28
S2	32282	(electroplating plating) and (diffuser diffusion)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 15:54
L14	5268	(electroplating plating) and rotat\$3 near2 (substrate workpiece wafer microelectronic semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 15:56
L15	5042	14 not semitool	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 15:56
L16	1296	15 and @py<"2000"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 15:57
L17	254	16 and ("204" "205").clas.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 16:00
L18	114	17 and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/14 16:00

## EAST Search History

L20	2	"2695269".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/14 18:06
S19	39	("3503856"   "3652442"   "3706651"   "3809642"   "3933601"   "3963588"   "4032422"   "4102756"   "4113577"   "4187154"   "4271790"   "4304641"   "4359375"   "4372825"   "4391694"   "4415423"   "4466864"   "4469566"   "4539079"   "4686014"   "4720329"   "4720330"   "4726884"   "4855020"   "4879007"   "4992145"   "5135636"   "5273642"   "5312532"   "5332487"   "5421987"   "5427674"   "5429733"   "5441629"   "5472592"   "5487824"   "5620581").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/14 18:06